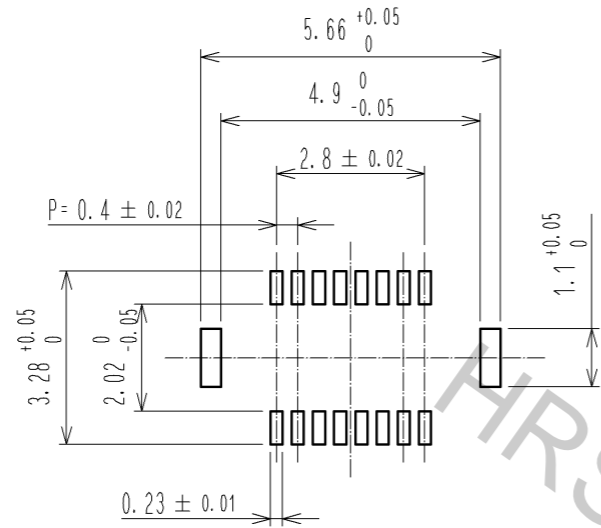


NOTE 1. ALL LEADS CO-PLANARITY SHALL BE 0.1mm MAX.
 ② CONTACT PLATING SPECIFICATIONS.
 CONTACT AREA : GOLD 0.1 μm MIN.
 SMT LEAD : GOLD 0.05 μm MIN.
 UNDERPLATING : NICKEL 1 μm MIN.
 (SURFACE : SEALING)
 ③ METAL HOLD DOWN PLATING SPECIFICATIONS.
 MOUNTING AREA: GOLD 0.05 μm MIN.
 UNDERPLATING : NICKEL 1 μm MIN.

3	PHOSPHOR BRONZE	③	7	PS	CLEAR(REINFORCEMENT COLLAR)
2	PHOSPHOR BRONZE	②	6	PS	BLACK(PLASTIC REEL)
1	LCP	UL94V-0. BLACK	5	POLYESTER	CLEAR(COVER TAPE)
			4	PS	CLEAR(EMBOSSED CARRIER TAPE)
NO.	MATERIAL	FINISH, REMARKS	NO.	MATERIAL	FINISH, REMARKS

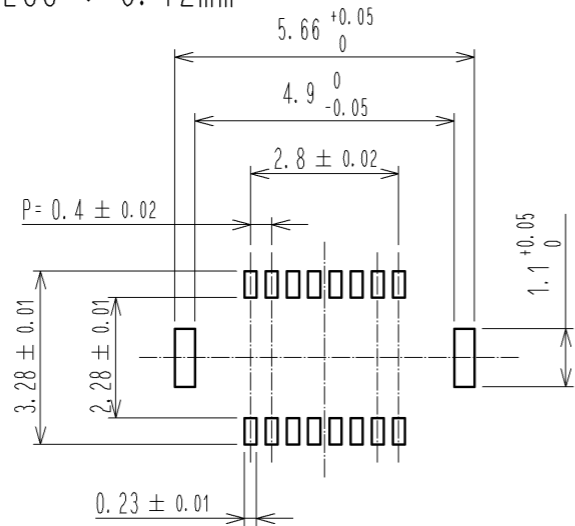
UNITS mm		SCALE FREE	COUNT 	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
HRS HIROSE ELECTRIC CO., LTD.		APPROVED : KH. IKEDA 14. 01. 20	DRAWING NO. EDC3-319635-02				
		CHECED : YH. MICHIDA 14. 01. 18	PART NO. DF37NB-16DS-0. 4V(75)				
		DISIGNED : YN. SAKAMOTO 14. 01. 18	CODE NO. CL684-3302-9-75				
		DRAWN : KR. AJITO 14. 01. 18					

◆ RECOMMENDED PCB LAYOUT(MOUNTING SURFACE SIDE)



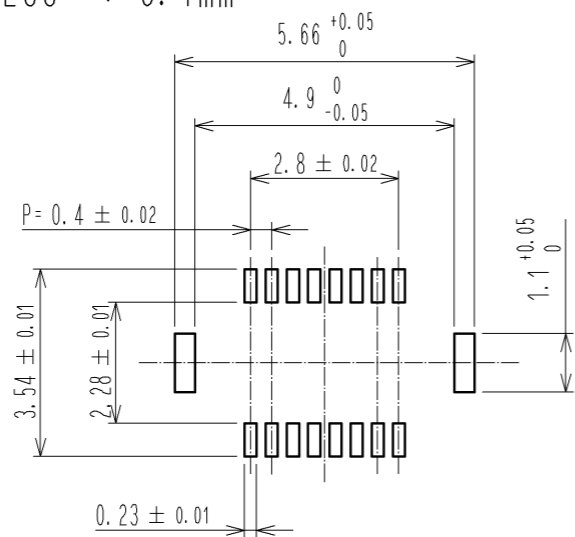
◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 0.12mm

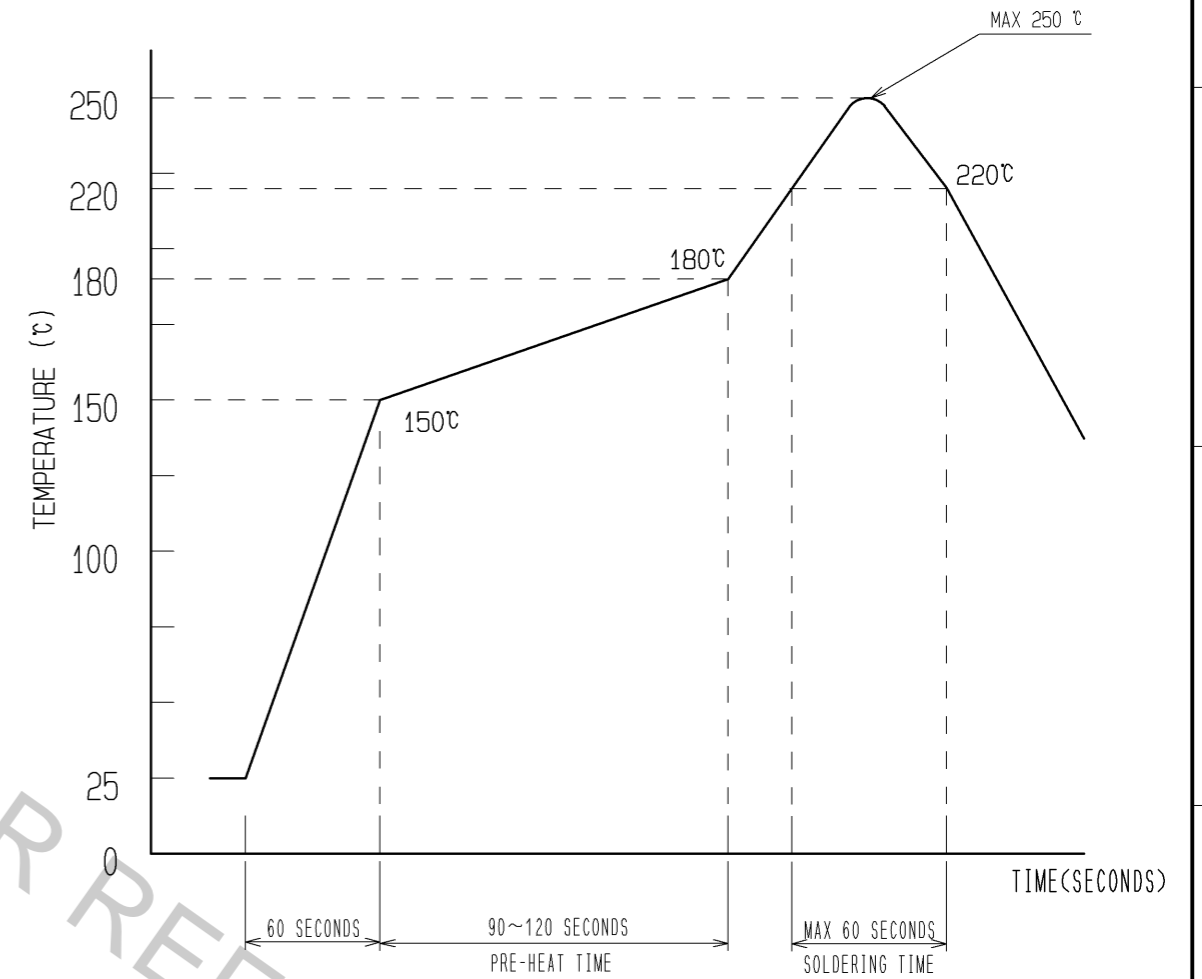


◆ RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 0.1mm



4 RECOMMENDED REFLOW TEMPERATURE PROFILE USING LEAD-FREE SOLDER PASTE.

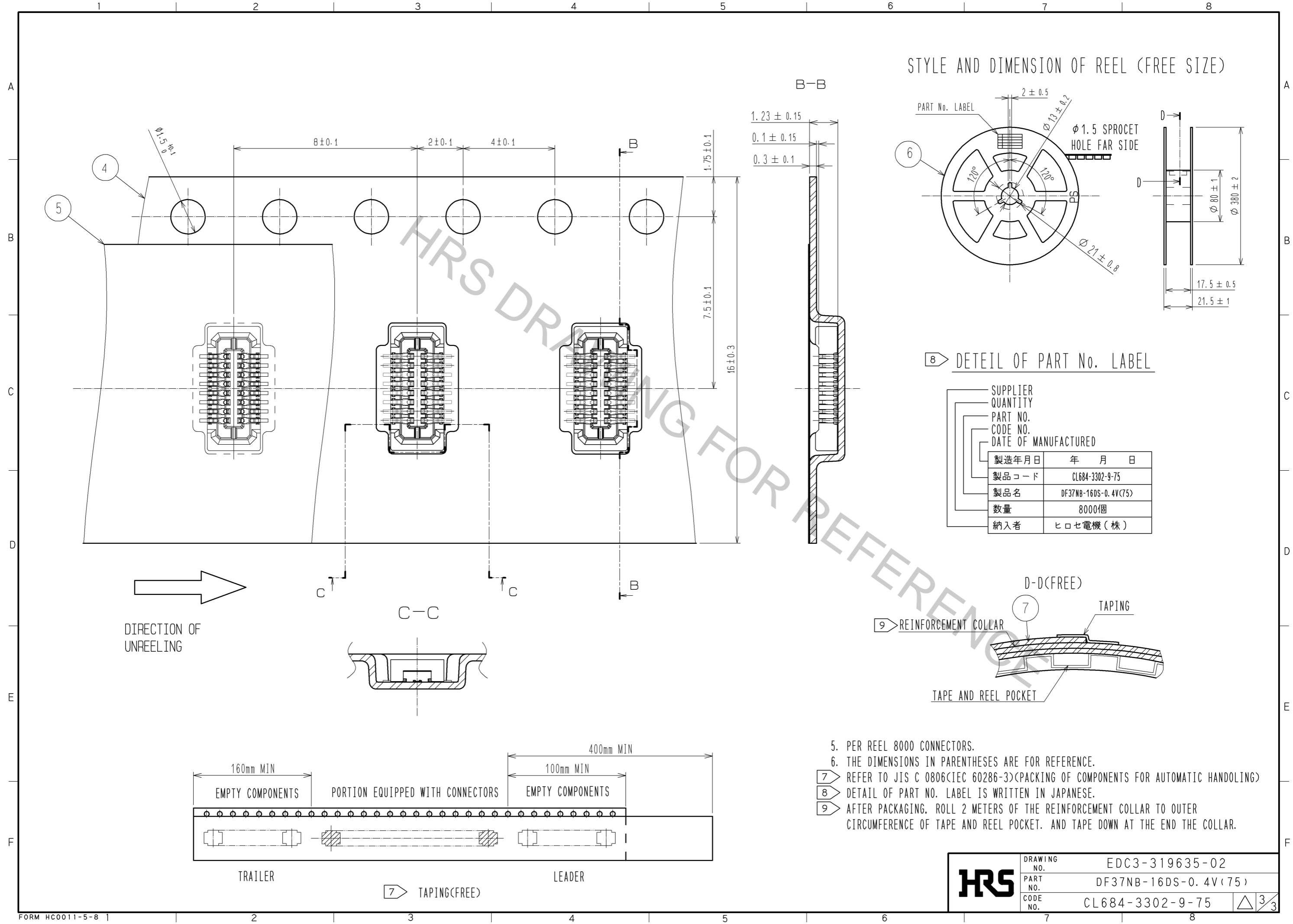


- 1) REFLOW TIME
 REFLOW METHOD: IR REFLOW
 NUMBER OF REFLOW CYCLES: 2 CYCLES MAX.
 DURATION ABOVE 220 °C: 60 SEC. MAX.
 (PEAK TEMPERATURE: 250°C MAX.)
- 2) PRE-HEAT TIME
 PRE-HEAT TEMPERATURE(MIN) : 150 °C
 PRE-HEAT TEMPERATURE(MAX) : 180 °C
 PRE-HEAT TIME : 90~120 sec.

4 THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS, SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.



DRAWING NO.	EDC3-319635-02
PART NO.	DF37NB-16DS-0.4V(75)
CODE NO.	CL684-3302-9-75



HRS	DRAWING NO.	EDC3-319635-02
	PART NO.	DF37NB-16DS-0.4V(75)
	CODE NO.	CL684-3302-9-75
		$\triangle 3/3$